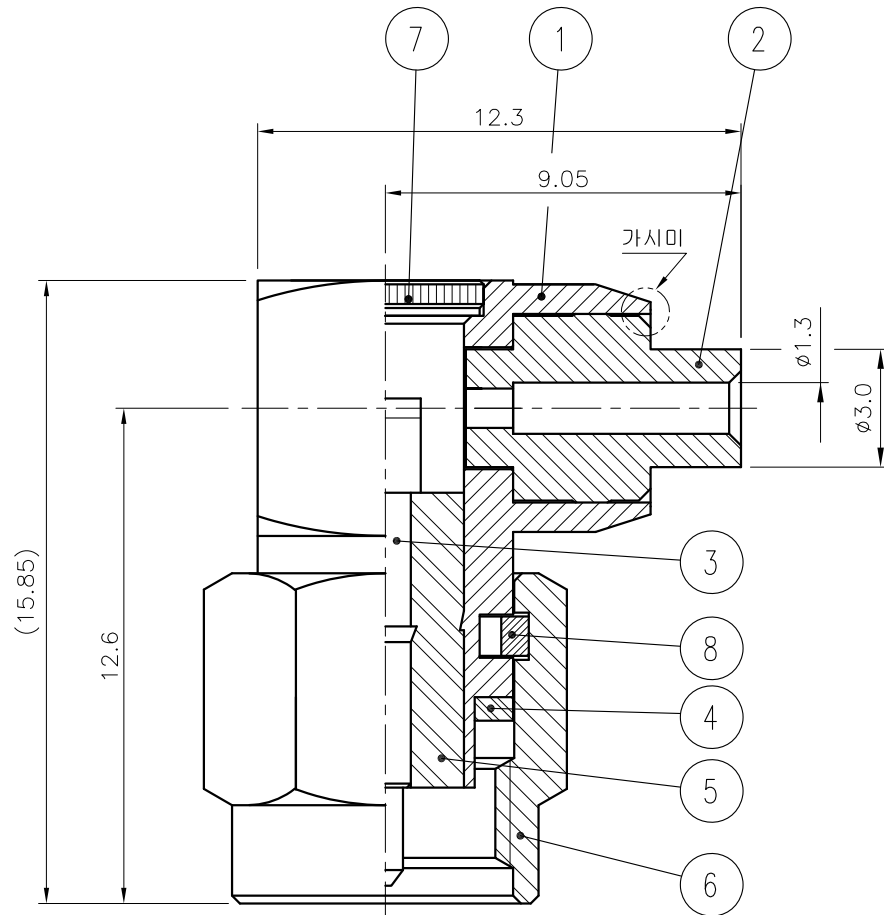
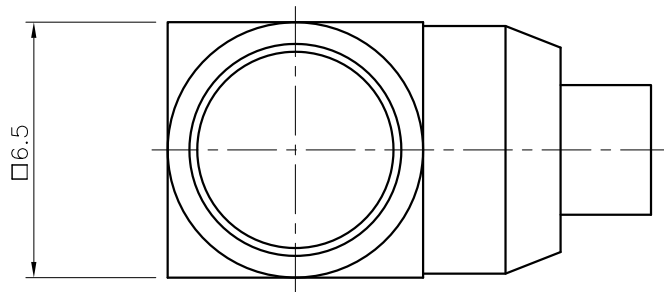


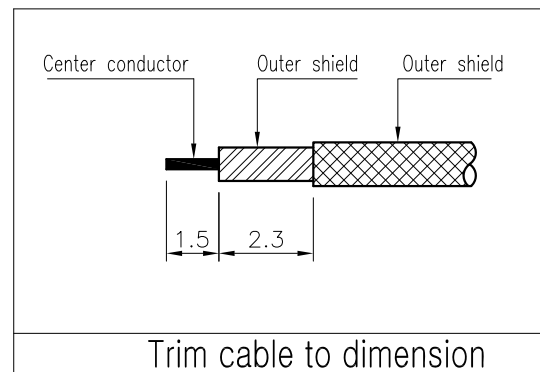


■조립순서

- 1번 바디에 5번 절연체 조립 이후 3번 핀 조립
- 1번 바디에 2번 바디 억지끼움 후 가시미 작업
- 6번 절연 절연체를 넣고 8번 COVER를 억지끼움
- 4번 GASKET 조립, 9번 C-RING, 7번 CAP을 조립

REVISION

REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2018.09.28.
i	[설번처리No.201812-0005] 금형바디 공용화로 인한 변경	S.Y.EUN	I.C.KIM	2018.12.19.



8	RING	1	SUS	부동태 처리	DSR00002-5/1
7	COVER	1	MBsBD C3604BD-F	Nickel Plate	DCO00114-5/1
6	CAP	1	MBsBD C3604BD-F	Nickel Plate	DCU00005-5/2
5	INSULATOR	1	TEFLON		DIN01015-N/1
4	GASKET	1	SILICONE RUB		DGK00004-N/1
3	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT00300-5/1
2	BODY (B)	1	MBsBD C3604BD-F	Gold Plate	DBD03252-5/2
1	BODY (A)	1	ZnDC	Nickel Plate (3~4μm)	DBD02994-5/3 DBD02883-5/3
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	±0.2	2018. 12. 19.				
	Angle	APPROVED BY	I.C.KIM			
MATERIAL		CHECKED BY	TITLE			
FINISH		DRAWN BY	S.Y.EUN			
		SCALE	UNIT			
		5/1	mm			
				A4		
				DWG NO. CN02748-7/4		
				REVISION 1 SHEET 1 of 1		